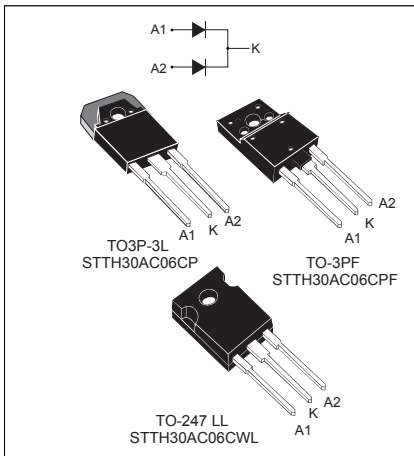


Turbo 2 ultrafast high voltage rectifier



Features

- Ultrafast switching
- Low reverse current
- Low thermal resistance
- Reduces switching and conduction losses
- Insulated package TO-3PF:
 - Insulated voltage: 2500 V_{DC}

Description

The **STTH30AC06C** uses ST Turbo 2 600 V technology. It is suited as boost diode specially for use in air conditioning equipment as continuous mode interleaved power factor correction.

Product status link

[STTH30AC06C](#)

Product summary

I_{F(AV)}	2 x 15 A
V_{RRM}	600 V
t_{rr} (typ)	40 ns
V_F (typ)	1.15 V
T_j	175 °C

1 Characteristics

Table 1. Absolute ratings (limiting values per diode at 25 °C, unless otherwise specified)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		600	V
$I_{F(RMS)}$	Forward rms current		30	A
$I_{F(AV)}$	Average forward current	Per diode	15	A
		Per device	30	
I_{FSM}	Surge non repetitive forward current	$t_p = 10$ ms sinusoidal	140	A
T_{stg}	Storage temperature range		-65 to +175	°C
T_j	Maximum operating junction temperature		175	°C

Table 2. Thermal parameters

Symbol	Parameter		Max. value	Unit	
$R_{th(j-c)}$	Junction to case	TO3P-3L, TO247 LL	Per diode	1.5	°C/W
			Total	0.85	
		TO-3PF	Per diode	3.5	
			Total	2.7	
$R_{th(c)}$	Coupling	TO3P-3L, TO247 LL)	0.2		
		TO-3PF	1.9		

Table 3. Static electrical characteristics (per diode)

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25$ °C	$V_R = V_{RRM}$	-		10	µA
		$T_j = 150$ °C		-	40	400	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25$ °C	$I_F = 15$ A	-		1.95	V
		$T_j = 150$ °C		-	1.15	1.45	
		$T_j = 25$ °C	$I_F = 30$ A	-		2.25	
		$T_j = 150$ °C		-	1.42	1.8	

1. Pulse test: $t_p = 5$ ms, $\delta < 2\%$

2. Pulse test: $t_p = 380$ µs, $\delta < 2\%$

To evaluate the conduction losses, use the following equation:

$$P = 1.1 \times I_{F(AV)} + 0.023 \times I_{F(RMS)}^2$$

Table 4. Dynamic characteristics (per diode)

Symbol	Parameters	Test conditions		Min.	Typ.	Max.	Unit
t_{rr}	Reverse recovery time	$T_j = 25\text{ °C}$	$I_F = 0.5\text{ A}, I_{rr} = 0.25\text{ A}, I_R = 1\text{ A}$	-		30	ns
			$I_F = 1\text{ A}, dI_F/dt = 50\text{ A}/\mu\text{s}, V_R = 30\text{ V}$	-	40	55	
I_{RM}	Reverse recovery current	$T_j = 125\text{ °C}$	$I_F = 15\text{ A}, dI_F/dt = 100\text{ A}/\mu\text{s}, V_R = 400\text{ V}$	-	4	5.5	A
t_{fr}	Forward recovery time	$T_j = 25\text{ °C}$	$I_F = 15\text{ A}, dI_F/dt = 100\text{ A}/\mu\text{s}, V_{FR} = 1.9\text{ V}$	-		100	ns
V_{FP}	Forward recovery voltage			-	2.5		V

1.1 Characteristics (curves)

Figure 1. Average forward power dissipation versus average forward current (per diode)

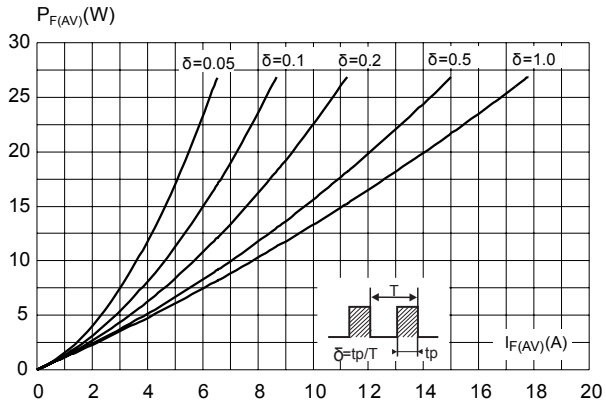


Figure 2. Forward voltage drop versus forward current (typical values, per diode)

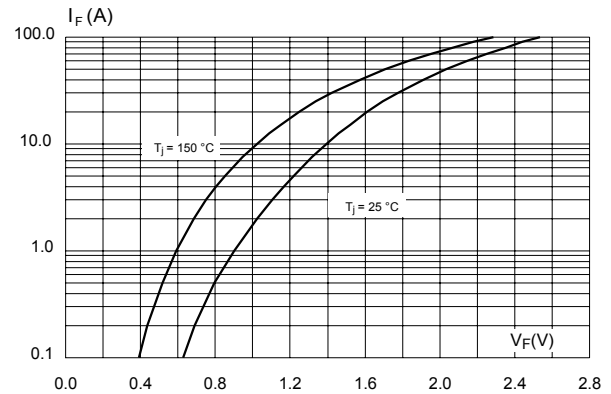


Figure 3. Forward voltage drop versus forward current (maximum values, per diode)

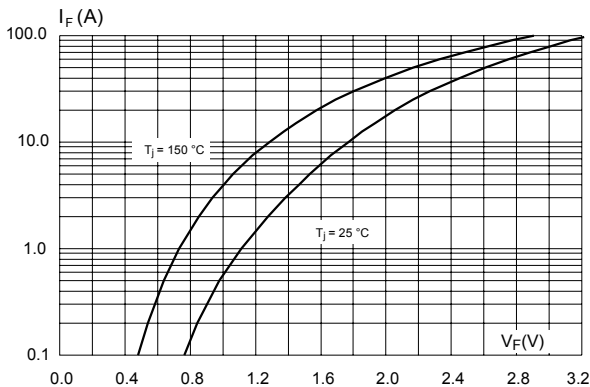


Figure 4. Relative variation of thermal impedance, junction to case, versus pulse duration (TO3P-3L, TO247 LL)

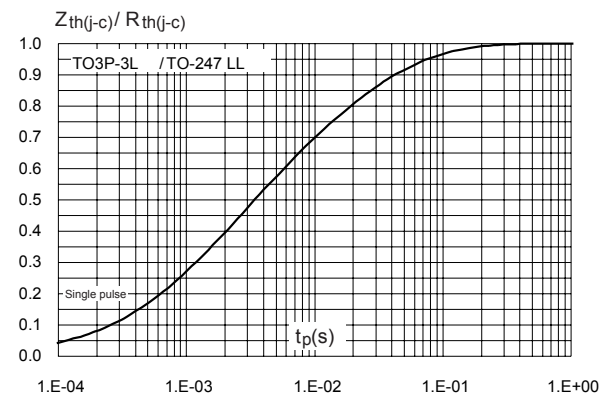


Figure 5. Relative variation of thermal impedance, junction to case, versus pulse duration (TO3P-3L)

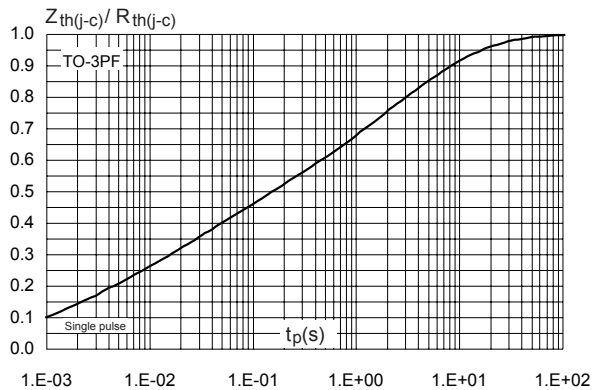


Figure 6. Peak reverse recovery current versus di_F/dt (typical values, per diode)

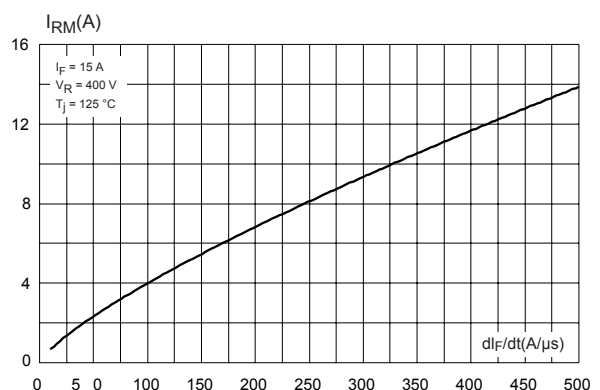


Figure 7. Reverse recovery time versus di_F/dt (typical values, per diode)

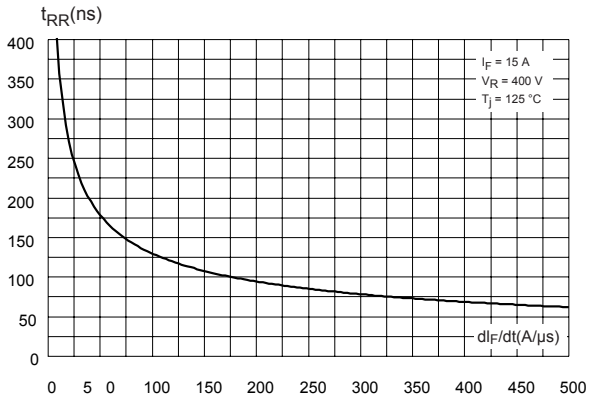


Figure 8. Reverse recovery charges versus di_F/dt (typical values, per diode)

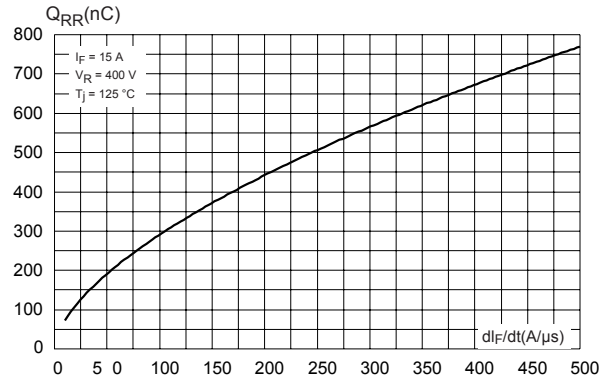


Figure 9. Reverse recovery softness factor versus di_F/dt (typical values, per diode)

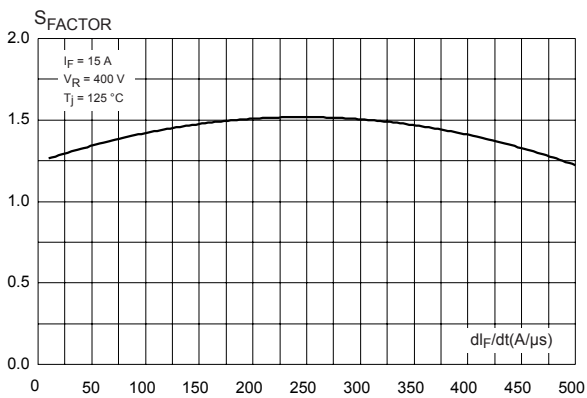


Figure 10. Relative variations of dynamic parameters versus junction temperature

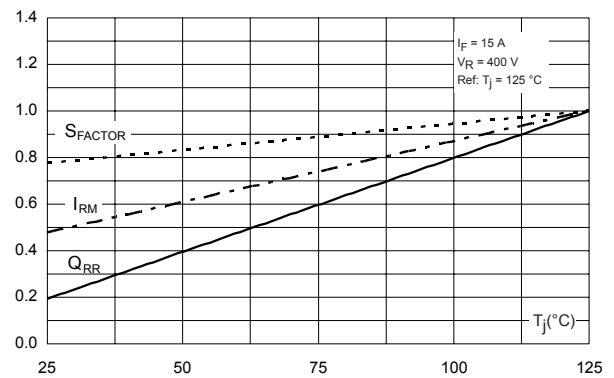


Figure 11. Transient peak forward voltage versus di_F/dt (typical values, per diode)

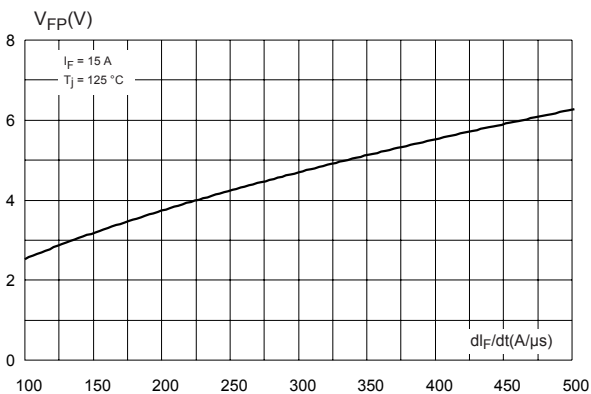


Figure 12. Forward recovery time versus di_F/dt (typical values, per diode)

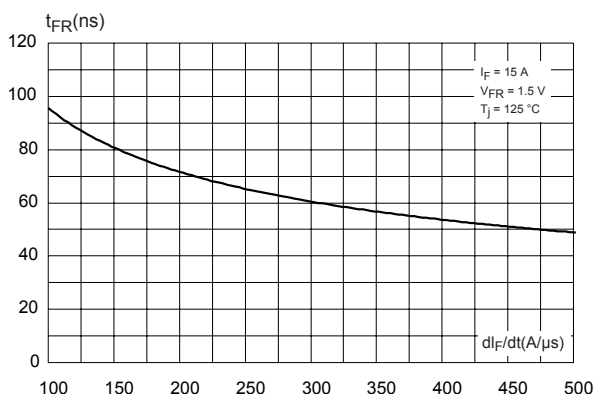
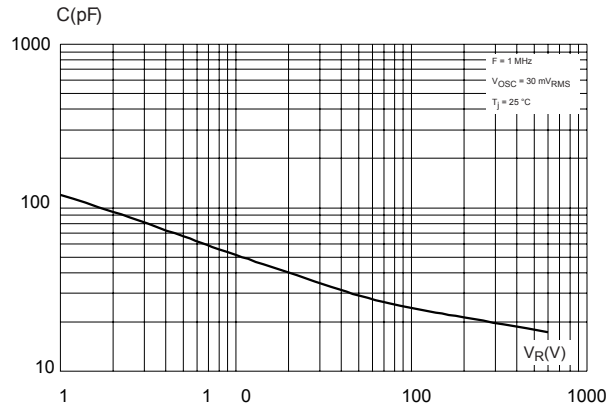


Figure 13. Junction capacitance versus reverse voltage applied (typical values, per diode)



2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

2.1 TO3P-3L package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque: 0.8 to 1.0 N·m

Figure 14. TO3P-3L package outline

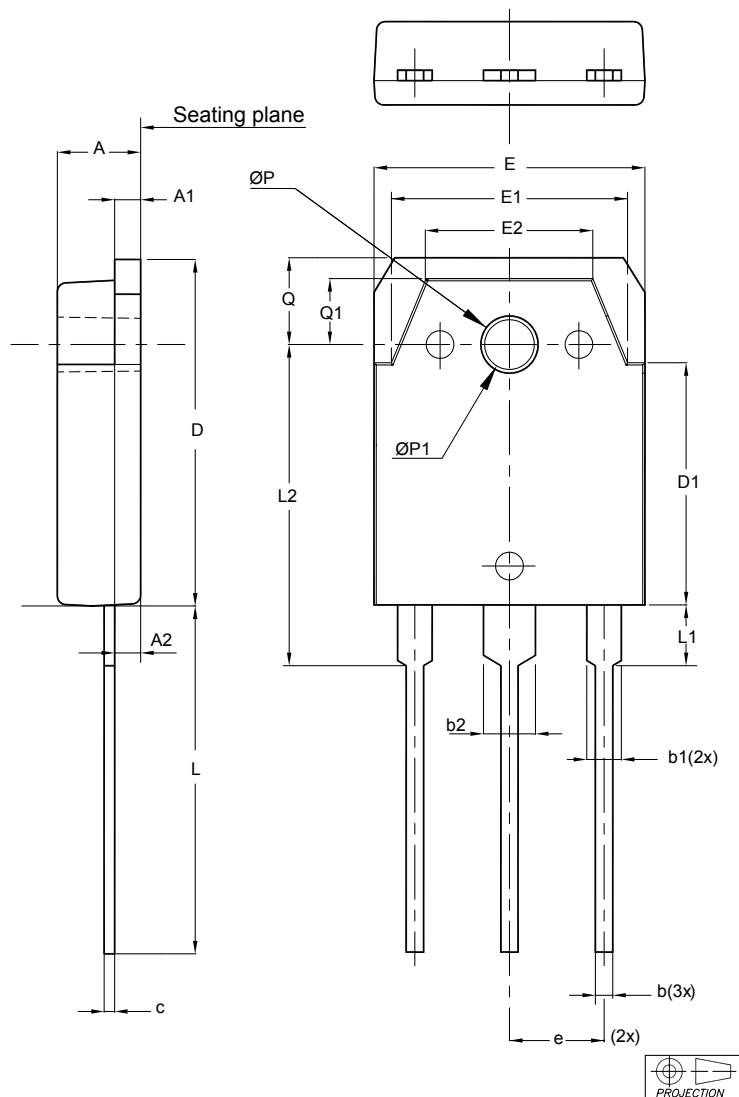


Table 5. TO3P-3L package mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.60	4.80	5	0.18	0.19	0.19
A1	1.45	1.50	1.65	0.05	0.06	0.06
A2	1.20	1.40	1.60	0.04	0.05	0.06
b	0.80	1.00	1.20	0.03	0.04	0.05
b1	1.80	2.00	2.20	0.07	0.08	0.08
b2	2.80	3.00	3.20	0.11	0.12	0.12
c	0.55	0.60	0.75	0.02	0.02	0.03
D	19.70	19.90	20.10	0.77	0.78	0.79
D1	13.70	13.90	14.10	0.54	0.54	0.55
E	15.40	15.60	15.80	0.60	0.61	0.62
E1	13.40	13.60	13.80	0.53	0.53	0.54
E2	9.40	9.60	9.90	0.37	0.38	0.39
e	5.15	5.45	5.75	0.20	0.21	0.22
L	19.80	20	20.20	0.78	0.78	0.79
L1	3.30	3.50	3.70	0.13	0.14	0.14
L2	18.20	18.40	18.60	0.71	0.72	0.73
Diam. P	3.30	3.40	3.50	0.13	0.13	0.14
Diam. P1	3.10	3.20	3.30	0.12	0.12	0.13
Q	4.80	5	5.20	0.19	0.19	0.20
Q1	3.60	3.80	4	0.14	0.15	0.16

2.2 TO-3PF package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque: 0.8 to 1.0 N·m

Figure 15. TO-3PF package outline

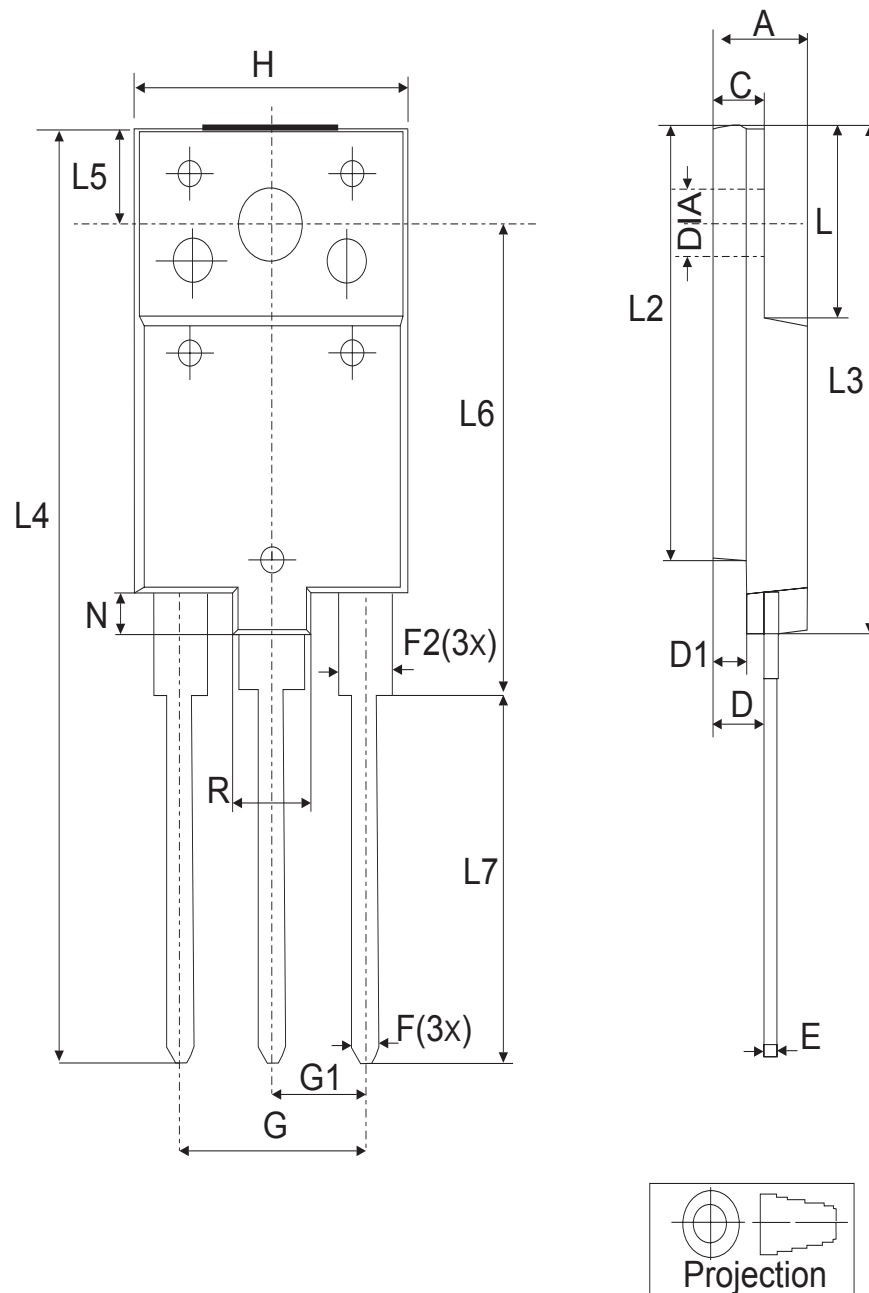


Table 6. TO-3PF mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	5.30		5.70
C	2.80		3.20
D	3.10		3.50
D1	1.80		2.20
E	0.80		1.10
F	0.65		0.95
F2	1.80		2.20
G	10.30		11.50
G1		5.45	
H	15.30		15.70
L	9.80	10	10.20
L2	22.80		23.20
L3	26.30		26.70
L4	43.20		44.40
L5	4.30		4.70
L6	24.30		24.70
L7	14.60		15
N	1.80		2.20
R	3.80		4.20
Dia	3.40		3.80

2.3 TO-247 long leads package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Maximum torque value: 1.0 N·m

Figure 16. TO-247 long leads package outline

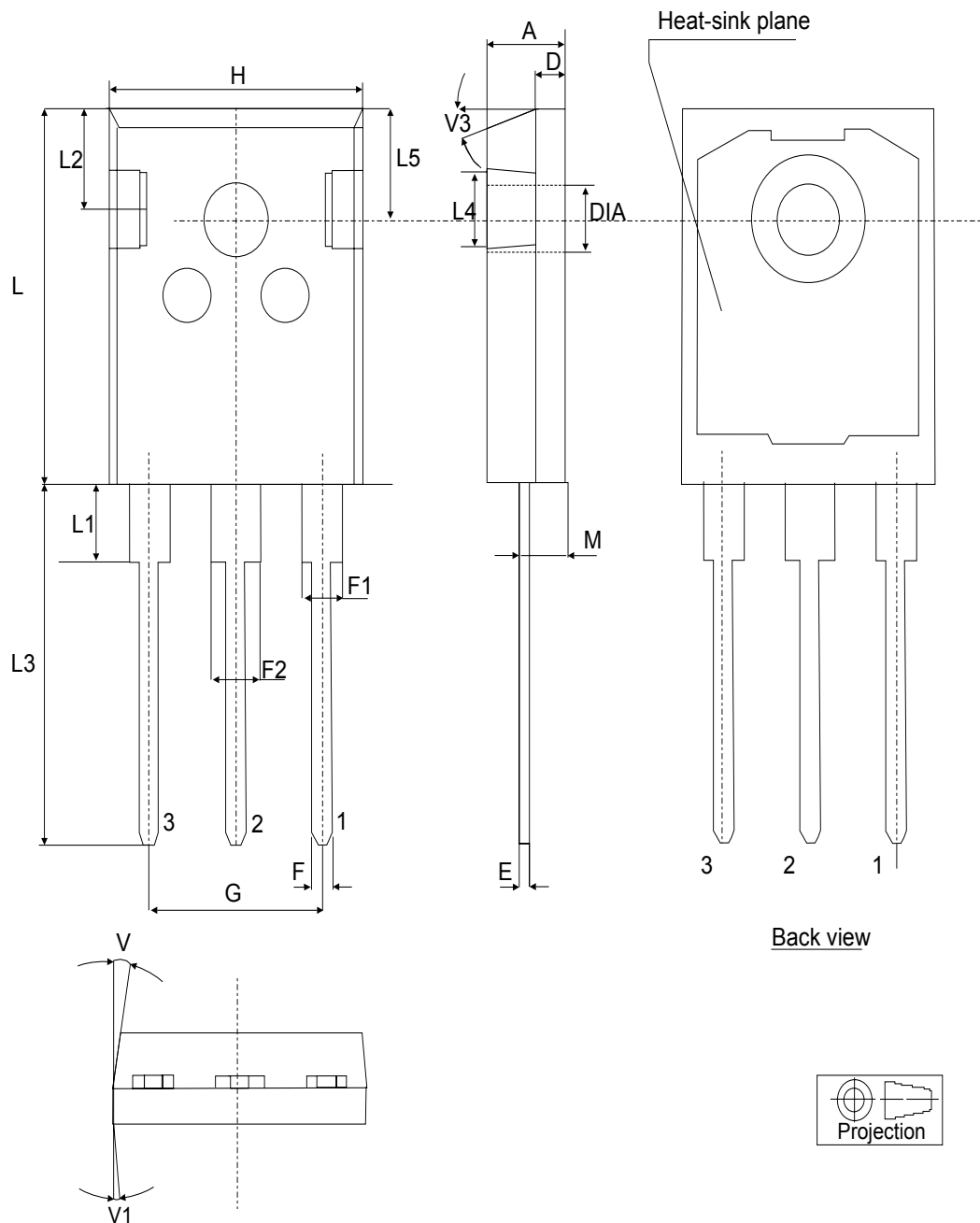


Table 7. TO-247 long leads package mechanical data

Dim.	mm.			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.90		5.15	0.192		0.202
D	1.85		2.10	0.072		0.082
E	0.55		0.67	0.021		0.026
F	1.07		1.32	0.042		0.051
F1	1.90		2.38	0.074		0.093
F2	2.87		3.38	0.110		0.133
G	10.90 BSC			0.429 BSC		
H	15.77		16.02	0.620		0.630
L	20.82		21.07	0.810		0.820
L1	4.16		4.47	0.163		0.175
L2	5.49		5.74	0.216		0.225
L3	20.05		20.30	0.789		0.799
L4	3.68		3.93	0.144		0.154
L5	6.04		6.29	0.237		0.247
M	2.25		2.55	0.088		0.100
V		10°			10°	
V1		3°			3°	
V3		20°			20°	
DIA	3.55		3.66	0.139		0.143

3 STTH30AC06C Ordering information

Table 8. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STTH30AC06CP	STTH30AC06C	TO3P-3L	5.26 g	30	Tube
STTH30AC06CPF	TH30AC06C	TO-3PF	5.6 g	30	
STTH30AC06CWL	STTH30AC06CWL	TO-247 LL	4.36 g	30	

Revision history

Table 9. Document revision history

Date	Version	Changes
13-Nov-2013	1	Initial release.
25-Jun-2015	2	Update of cover page and Table 7. Format updated to current standard.
01-Jul-2015	3	Updated Features.
05-Sep-2016	4	Updated Figure 16.
18-Apr-2018	5	Updated TO247LL POA drawing.

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2018 STMicroelectronics – All rights reserved